main surface 114 of the SAW substrate 112. The sealing wall 126 is formed so as to enclose an SAW device formed on the SAW substrate 112. The SAW device is hermetically sealed by the SAW substrate 112, quartz substrate 124 and sealing wall 126. The comb-shaped electrodes 116, 118, 120 and 122 extend beyond the sealing wall 126 so that their extremities, i.e., electrodes pads 128, 130, 132 and 134 are connected via bonding wires not shown to a circuit board not shown. In the step of assembling such two substrates into the electronic component 110, the assembly is typically carried out for each electronic component.--

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REMARKS

Applicants further amend the paragraph beginning on page 2, line 5 so the terms FIG. 20A and FIG. 20B are properly used throughout that amended paragraph.

If the Examiner has any questions regarding matters pending in this application, please feel free to contact the undersigned below.

Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page is captioned **"VERSION WITH MARKINGS TO SHOW CHANGES MADE"**.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE SPECIFICATION

Paragraph beginning at page 2, line 5 has been amended as follows:

-- Referring to FIGs. ~~12A~~ 20A and ~~12B~~20B, an electronic component is shown having a structure that is disclosed in "Optimizing AQP SAW Resonators for Reduced Vibration Sensitivity" published in IEEE Ultrasonic Symposium, 1995. FIG. ~~12A~~ 20A is a side elevation of an electronic component 110; and FIG. ~~12B~~ 20B is a sectional view of the same taken along a line A-A of FIG. ~~12A~~20A. The electronic component 110 is an SAW resonator. The SAW resonator includes comb-shaped electrodes 116, 118, 120 and 122 that are formed on a main surface 114 of an SAW substrate 112. A glass sealing wall 126 is formed on a quartz substrate 124 and is fused to the main surface 114 of the SAW substrate 112. The sealing wall 126 is formed so as to enclose an SAW device formed on the SAW substrate 112. The SAW device is hermetically sealed by the SAW substrate 112, quartz substrate 124 and sealing wall 126. The comb-shaped electrodes 116, 118, 120 and 122 extend beyond the sealing wall 126 so that their extremities, i.e., electrodes pads 128, 130, 132 and 134 are connected via bonding wires not shown to a circuit board not shown. In the step of assembling such two substrates into the electronic component 110, ~~the assembly is typically carried out for each electronic component.~~--

C1

Paragraph beginning at page 5, line 25 has been amended as follows:

-- When fabricating the electronic component 110 depicted in FIGs. ~~12A~~ 20A and ~~12B~~20B, the sealing wall 126 may be heated upon fusing of the sealing wall 126 made of glass, polyimide resin or epoxy resin onto the main surface 114 of the SAW substrate 112, with the result that gas may be generated at the sealing wall fused portion. The thus generated gas may possibly attach to the SAW device electrodes inside the sealing wall, resulting in degradation of the SAW device characteristics.--

C2

IN THE CLAIMS

Claims 19 has been amended as follows:

19 (Amended). A method of manufacturing an electronic component according to claim 13, wherein

a first electrically conductive member is ~~previously~~ formed on an inner wall of each of said plurality of openings, said first electrically conductive member being electrically connectable to said circuit board, and wherein

said second step includes a step in which, a second electrically conductive member is formed on each of said plurality of electrode pads, said second electrically conductive member electrically connecting said first electrically conductive member and each of said plurality of electrode pads.